CHEMTRONICS Technical Data Sheet

TDS # CW8

Chemask® W

PRODUCT DESCRIPTION

Chemask® W solder mask is water soluble and designed to be removed with most aqueous cleaning systems. Chemask® W contains high temperature compounds that protect component-free areas from solder during wave soldering. This water soluble formulation is stable to rosin, organic and inorganic fluxes.

- Protects boards from molten solder to 515°F (268°C)
- Compatible with most flux types
- Leaves no corrosive residue
- Non-contaminating
- UV Detectable

TYPICAL APPLICATIONS

During wave soldering, Chemask® W protects:

- Component Free Areas
- Gold Connectors
- Gold Fingers
- Pin Connectors

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Base Material	Synthetic Resin		
Color	Blue		
Solvent Stability	Dissolves in water with or without detergent		
Flux Compatibility	Aqueous Flux		
Temperature Stability	515°F (268°C)		
Tack-Free Drying Time (10 mils @ 77°F)	e 20 min.		
Cure Time (10 mils @ 77°F)	1 hr.		
Viscosity (@ 77°F) (± 300 cps)	15,000 cps		
Viscosity Adjusted Wit	h DI Water		
Contains UV Indicator	Yes		
Solids Content	$\sim 40\%$		
Flash Point	Nonflammable		
Weight/Gallon	8.8 lbs.		
Shelflife	1 year		

COMPATIBILITY

Chemask® W is generally c ompatible with most materials used in printed circuit board fabrication. As with any solder masking agent, c ompatibility with substrate must be determined on a non-critical area prior to use.

APPLICATION METHOD Squeeze Bottle/Syringe Yes Spatula Yes Screening Yes Stencil Yes Automatic Dispensing Yes

USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

Chemask® W sol der masking a gent is engineered for a ll electronic manufacturing applications. When applying by hand using squeeze bottle or s patula, insure that a ll areas o f the p re-tinned hole a re e venly covered on the s ide to be so ldered. For screening applications, properly clean and prepare screen, then apply masking agent in the same manner as solder paste. Automatic dispensing e quipment m ay a lso be u sed as appropriate.

REMOVAL: After a llowing the m ask to become f ully c ured, the m ask m ay be washed a way w ith water. F or optimum performance, w ater soluble m ask m ay be removed w ith a gitation, u ltrasonic, or industrial w ashing. S urfactants m ay be added to increase cleaning efficiency.

AVAILABILITY

CW8 8 oz. Squeeze Bottle

TECHNICAL & APPLICATION ASSISTANCE

Chemtronics provides a technical hotline to answer your t echnical and ap plication r elated q uestions. The toll free number is: **1-800-TECH-401.**

ENVIRONMENTAL IMPACT DATA

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CFC	0.0%	VOC	5.0%	
HCFC	0.0%	HFC	0.0%	
Cl. Solv.	0.0%	ODP	0.00	

CFC, H CFC, C L. S OLV., V OC, a nd H FC num bers shown a re the content b y w eight. O zone de pletion potential (ODP) is d etermined i n accordance with t he Montreal Protocol and U.S. Clean Air Act of 1990. The ODP of this product is 0.0. It is the sum of the ODP of the s ubstances t hat m ay c ontribute to t he de pletion of stratospheric oz one, ba sed upon t he w eight o f e ach substance in the product's formulation.

NOTE:

This information is be lieved to be a ccurate. It is intended for professional end users having the skills to evaluate and uset hed at a properly. CHEMTRONICS does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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